



SEC.836

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re PATENT APPLICATION of:

Hyun-don OH et al.

Group Art Unit: 2829

Serial No.: 09/939,556

Examiner: Scott B. GEYER

Filed: 28 August 2001

EQUIPMENT FOR FABRICATING  
A SEMICONDUCTOR PRODUCT

RECEIVED  
JUN 26 2003  
TC 2800 MAIL ROOM

#7/Amdt B  
7/12/03  
C.P.

**AMENDMENT UNDER 37 C.F.R. § 1.112**

Honorable Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated 24 February 2003, the period for response to which is hereby being extended by the accompanying Petition and Petition Fee to 24 June 2003, please amend the above-identified patent application as follows:

**IN THE CLAIMS:**

Please substitute the following claims for the pending claims with the same claim numbers.

B<sup>1</sup> 4. (Amended) A semiconductor fabricating device, comprising:  
an adhesion unit installed in a production line, the adhesion unit having an  
adhesion chamber that supplies an adhesion enhancing material that reinforces